



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Douglas O. Powell

Serial No.: 09/665,366 ✓

Filed: September 19, 2000

For: ELECTRONIC INTERCONNECT
STRUCTURE AND METHOD FOR
MAKING

: Art Unit: 3726

: Examiner: Compton, Eric B.

: Atty Docket: EN9-99-026
(20135/00276)

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RESPONSE AND AMENDMENT UNDER 37 CFR § 1.111

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated January 22, 2003, please amend the above-identified application as follows:

IN THE CLAIMS:

Kindly amend the claims as follows:

1. A parallel joining technology method for making a multi-layer electronic structure, the method comprising:

providing a plurality of sub-composites, wherein each said sub-composite is formed by the steps of

providing a layer of dielectric material having a first surface and a second surface, wherein said first surface is selected from the group consisting of a top surface and a bottom surface,

providing a layer of electrically conducting material on said first surface;

forming at least one blind via comprising a passage from said second surface through said dielectric layer to expose said layer of electrically conducting material facing said dielectric layer;

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